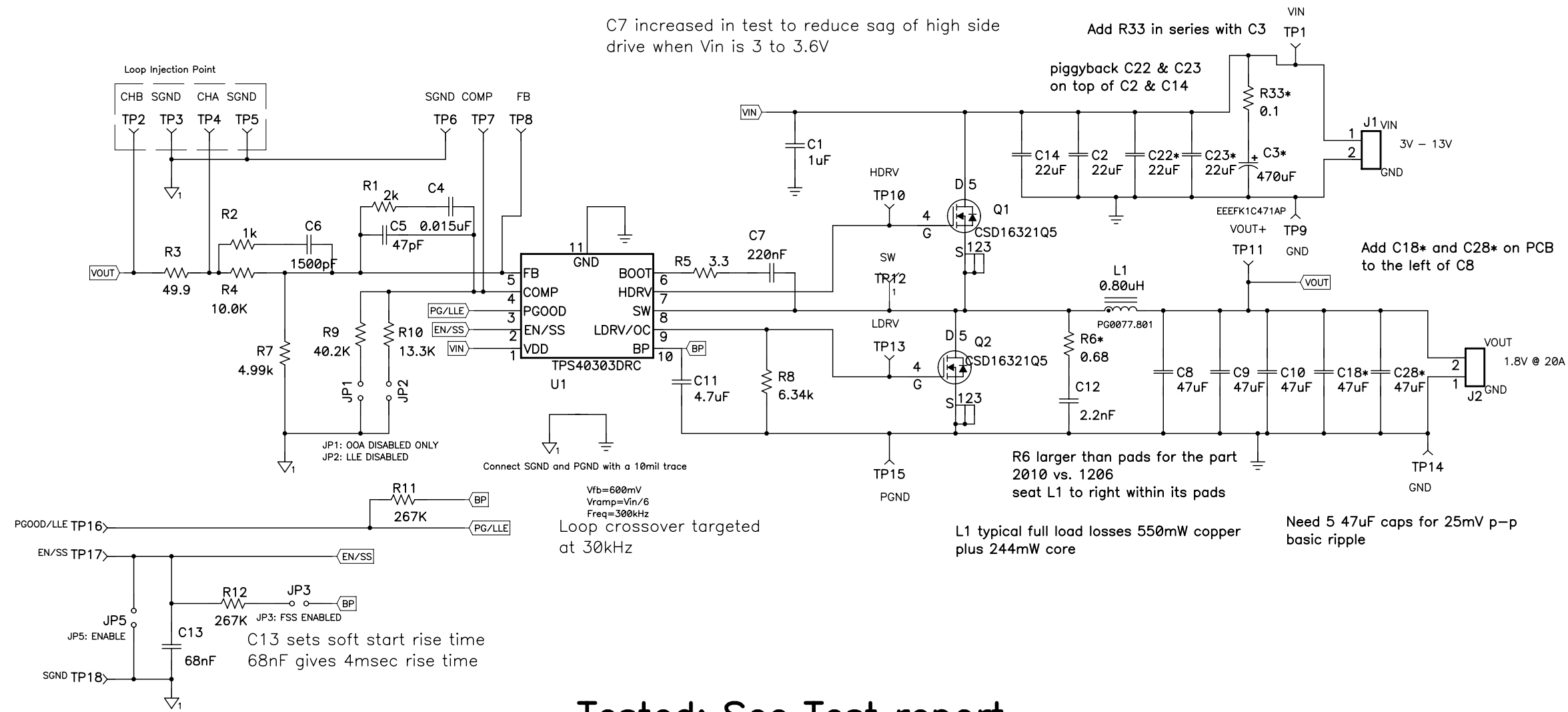


Q1 was originally CSD16323Q3 which worked OK at 12Vin, but got too hot at 3Vin where duty cycle rises to 65% for 1.8Vout. If I_{max} out is 15A or less at 3.3Vin then Q1 can be smaller part

R5 and R8 reduced when larger Q1 used. Were 6.8 ohms and 12.1k respectively with CSD16323Q3

C7 increased in test to reduce sag of high side drive when Vin is 3 to 3.6V



Tested: See Test report

Modified from HPA353 rev E2
by Todd Bellefeuille
Build on HPA353 rev E2 PCB

TEXAS INSTRUMENTS		
Title 3-13Vin to 1.8V 20A TPS40303		
Size C	Number PMP5032	Rev A
Date August 14, 2009	Drawn by Josh Mandelcorn	
Filename PMP5032_revA.SCH	Sheet 1 of 1	

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